Abstracts

A Non-Contact Interconnection through an Electrically Thick Ground Plate Common to Two Microstrip Lines

M. Davidovitz, R.A. Sainati and S.J. Fraasch. "A Non-Contact Interconnection through an Electrically Thick Ground Plate Common to Two Microstrip Lines." 1995 Transactions on Microwave Theory and Techniques 43.4 (Apr. 1995, Part I [T-MTT]): 753-759.

Coupling rectangular slot in a between two microstrip lines through a common, electrically thick ground plate is analyzed. The results are applied to examine the properties of a vertical, noncontact line-to-line transition. An efficient and accurate design model is constructed. The model allows insight into the coupling characteristics of the device with minimal computational effort. Measured results are used to verify the efficacy of the solution. Analytical or highly convergent forms of the model parameters are derived whenever possible.

❑ Return to main document.